

HD74HCT374, HD74HCT534

Octal D-type Flip-Flops (with 3-state outputs)

Octal D-type Flip-Flops (with inverted 3-state outputs)

REJ03D0667-0200
 (Previous ADE-205-556)
 Rev.2.00
 Mar 30, 2006

Description

These device are positive edge triggered flip-flops. The difference between HD74HCT374 and HD74HCT534 is only that the former is a true outputs and the latter is a false outputs. Data at the D inputs, meeting the setup and hold time requirements, are transferred to the Q outputs on positive going transitions of the clock (CK) input. When a high logic level is applied to the output control (OC) input, all outputs go to a high impedance state, regardless of what signals are present at the other inputs and the state of the storage elements.

Features

- LSTTL Output Logic Level Compatibility as well as CMOS Output Compatibility
- High Speed Operation: t_{pd} (Clock to Q) = 15 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 15 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 4.5$ to 5.5 V
- Low Input Current: $1 \mu\text{A}$ max
- Low Quiescent Supply Current: I_{CC} (static) = $4 \mu\text{A}$ max ($T_a = 25^\circ\text{C}$)
- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74HCT374P	DILP-20 pin	PRDP0020AC-B (DP-20NEV)	P	—
HD74HCT374FPEL HD74HCT534FPEL	SOP-20 pin (JEITA)	PRSP0020DD-B (FP-20DAV)	FP	EL (2,000 pcs/reel)
HD74HCT374RPEL HD74HCT534RPEL	SOP-20 pin (JEDEC)	PRSP0020DC-A (FP-20DBV)	RP	EL (1,000 pcs/reel)
HD74HCT374TELL	TSSOP-20 pin	PTSP0020JB-A (TTP-20DAV)	T	ELL (2,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

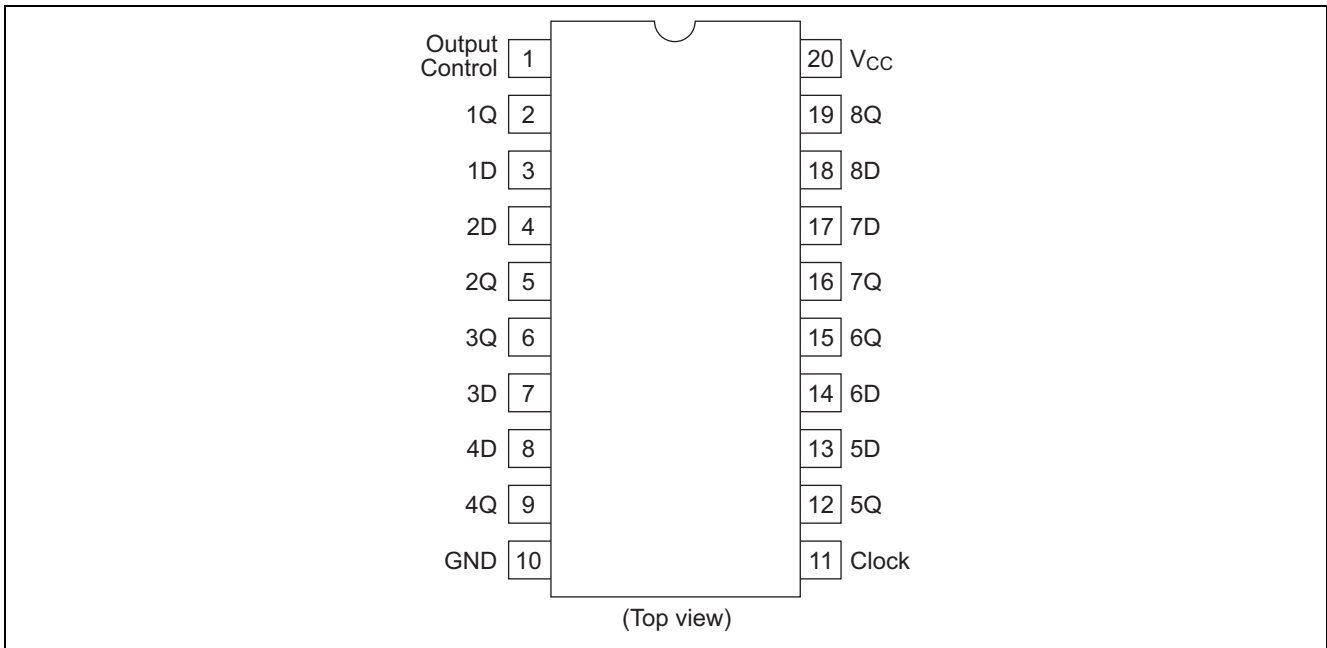
Function Table

Output Control	Clock	D	HD74HCT374 Q	HD74HCT534 \bar{Q}
L		H	H	L
L		L	L	H
L	L	X	No change	No change
H	X	X	Z	Z

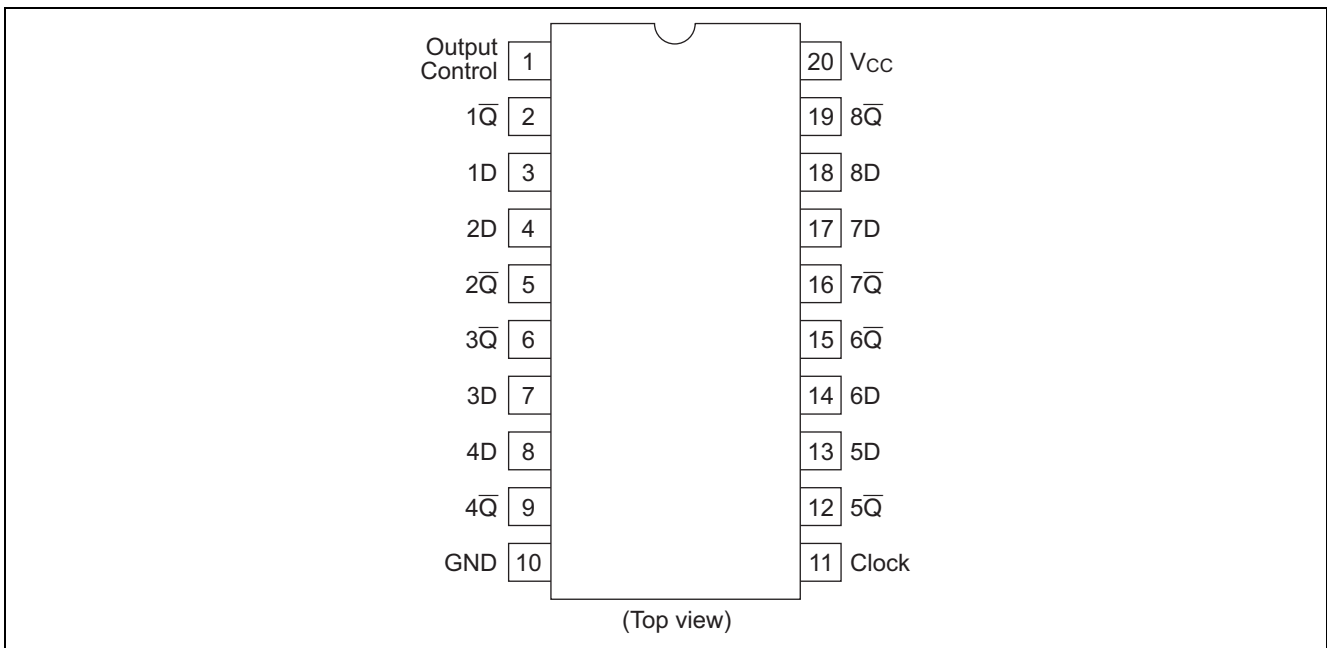
Notes: 1. H; High level, L; Low level, X; Irrelevant, Z; High impedance

Pin Arrangement

HD74HCT374

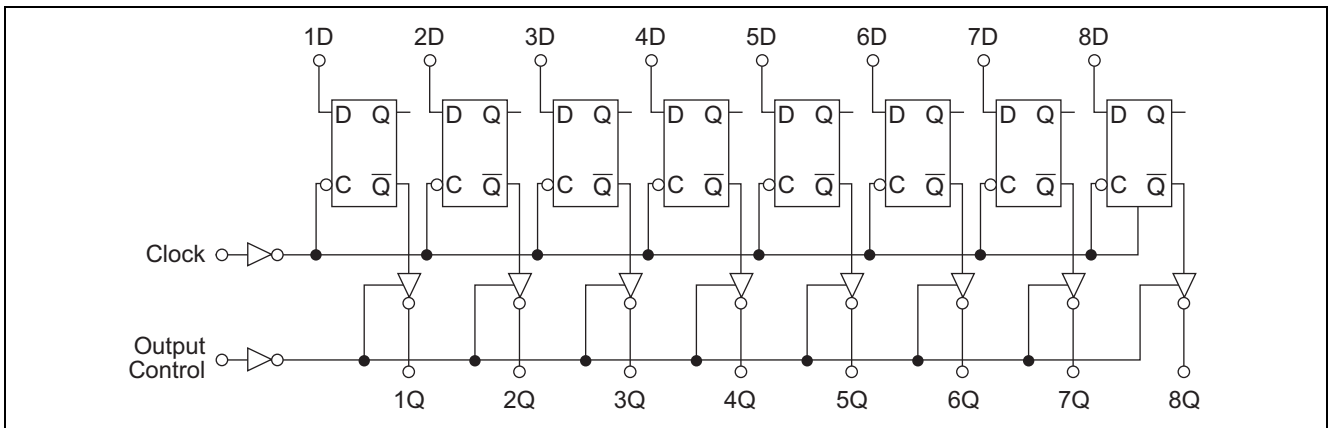


HD74HCT534

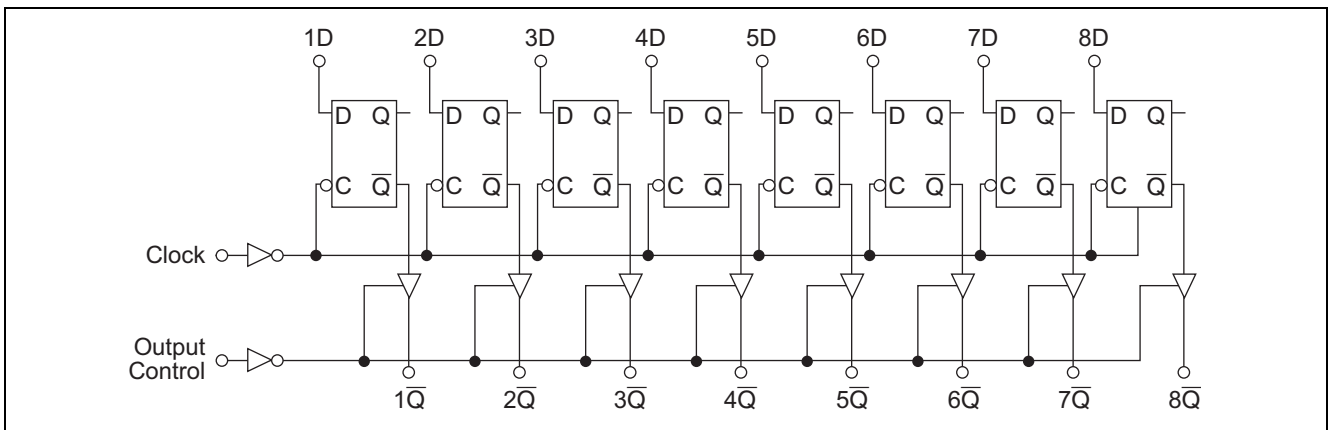


Logic Diagram

HD74HCT374



HD74HCT534



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage range	V_{CC}	-0.5 to 7.0	V
Input / Output voltage	V_{IN}, V_{OUT}	-0.5 to $V_{CC} + 0.5$	V
Input / Output diode current	I_{IK}, I_{OK}	± 20	mA
Output current	I_{OUT}	± 35	mA
V_{CC} , GND current	I_{CC} or I_{GND}	± 75	mA
Power dissipation	P_T	500	mW
Storage temperature	T_{stg}	-65 to +150	$^{\circ}C$

Note: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V_{CC}	4.5 to 5.5	V	
Input / Output voltage	V_{IN}, V_{OUT}	0 to V_{CC}	V	
Operating temperature	T_a	-40 to 85	$^{\circ}C$	
Input rise / fall time ^{*1}	t_r, t_f	0 to 500	ns	$V_{CC} = 4.5 V$

Notes: 1. This item guarantees maximum limit when one input switches.

Waveform: Refer to test circuit of switching characteristics.

Electrical Characteristics

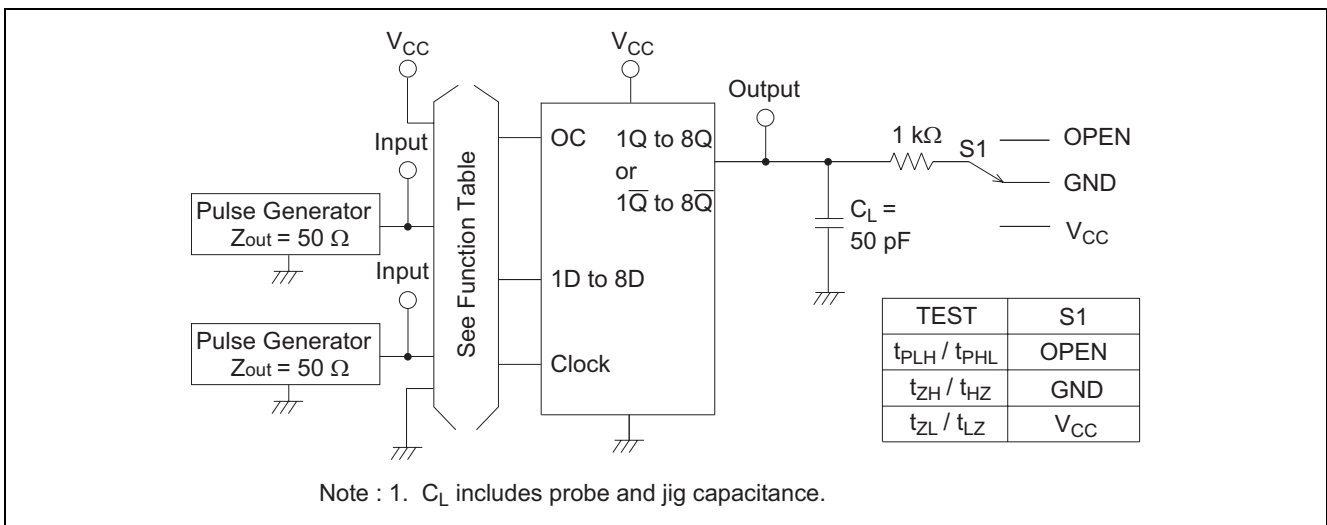
Item	Symbol	V _{CC} (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Input voltage	V _{IH}	4.5 to 5.5	2.0	—	—	2.0	—	V		
	V _{IL}	4.5 to 5.5	—	—	0.8	—	0.8	V		
Output voltage	V _{OH}	4.5	4.4	—	—	4.4	—	V	Vin = V _{IH} or V _{IL}	I _{OH} = -20 μA
		4.5	4.18	—	—	4.13	—			I _{OH} = -6 mA
	V _{OL}	4.5	—	—	0.1	—	0.1	V	Vin = V _{IH} or V _{IL}	I _{OL} = 20 μA
		4.5	—	—	0.26	—	0.33			I _{OL} = 6 mA
Off-state output current	I _{OZ}	5.5	—	—	±0.5	—	±5.0	μA	Vin = V _{IH} or V _{IL} , Vout = V _{CC} or GND	
Input current	I _{in}	5.5	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND	
Quiescent current	I _{CC}	5.5	—	—	4.0	—	40	μA	Vin = V _{CC} or GND, Iout = 0 μA	

Switching Characteristics

(C_L = 50 pF, Input t_r = t_f = 6 ns)

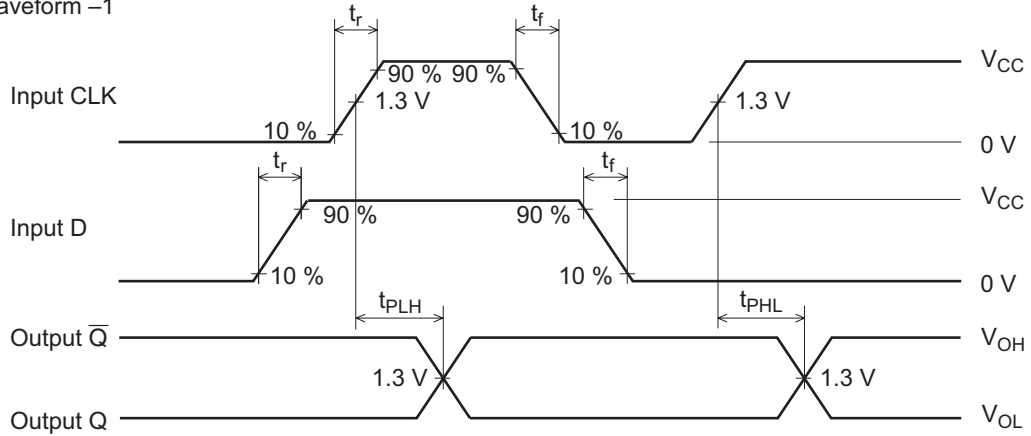
Item	Symbol	V _{CC} (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Maximum clock frequency	f _{max}	4.5	—	—	30	—	24	MHz		
Propagation delay time	t _{PLH}	4.5	—	12	28	—	35	ns		
	t _{PHL}	4.5	—	15	28	—	35			
Output enable time	t _{ZL}	4.5	—	16	30	—	38	ns		
	t _{ZH}	4.5	—	15	30	—	38			
Output disable time	t _{LZ}	4.5	—	13	30	—	38	ns		
	t _{HZ}	4.5	—	16	30	—	38			
Setup time	t _{su}	4.5	20	2	—	25	—	ns	Data to clock	
Hold time	t _h	4.5	5	0	—	6	—	ns	Clock to data	
Pulse width	t _w	4.5	16	5	—	20	—	ns	Clock, output control	
Output rise/fall time	t _{TLH}	4.5	—	4	12	—	15	ns		
	t _{THL}									
Input capacitance	C _{in}	—	—	5	10	—	10	pF		

Test Circuit

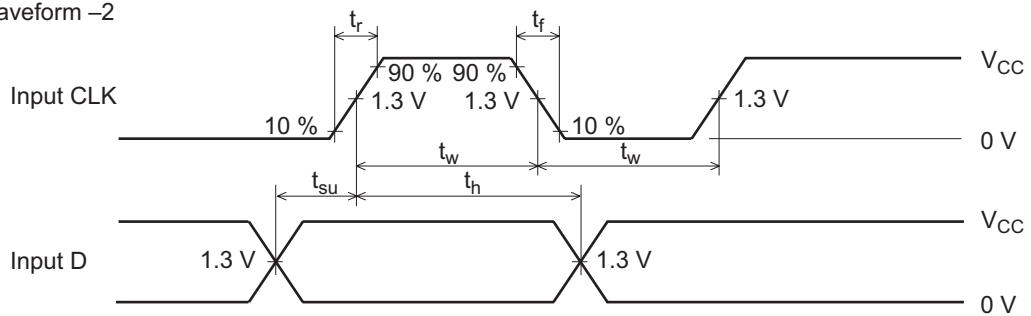


Waveforms

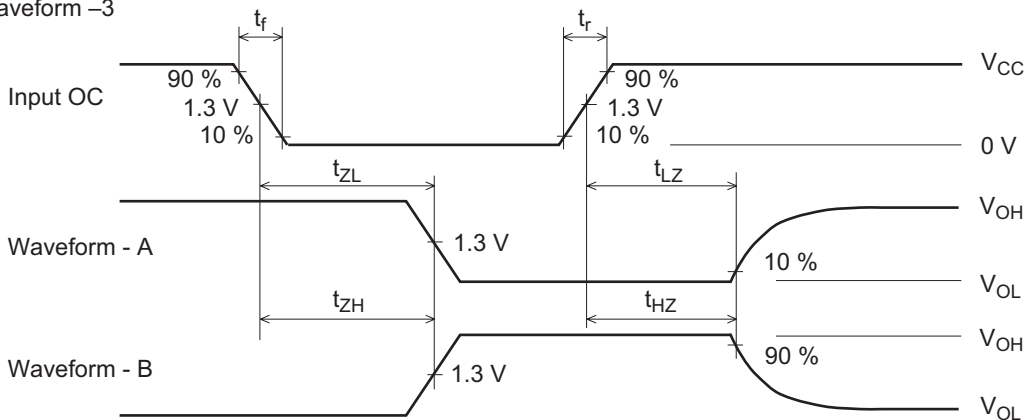
• Waveform –1



• Waveform –2

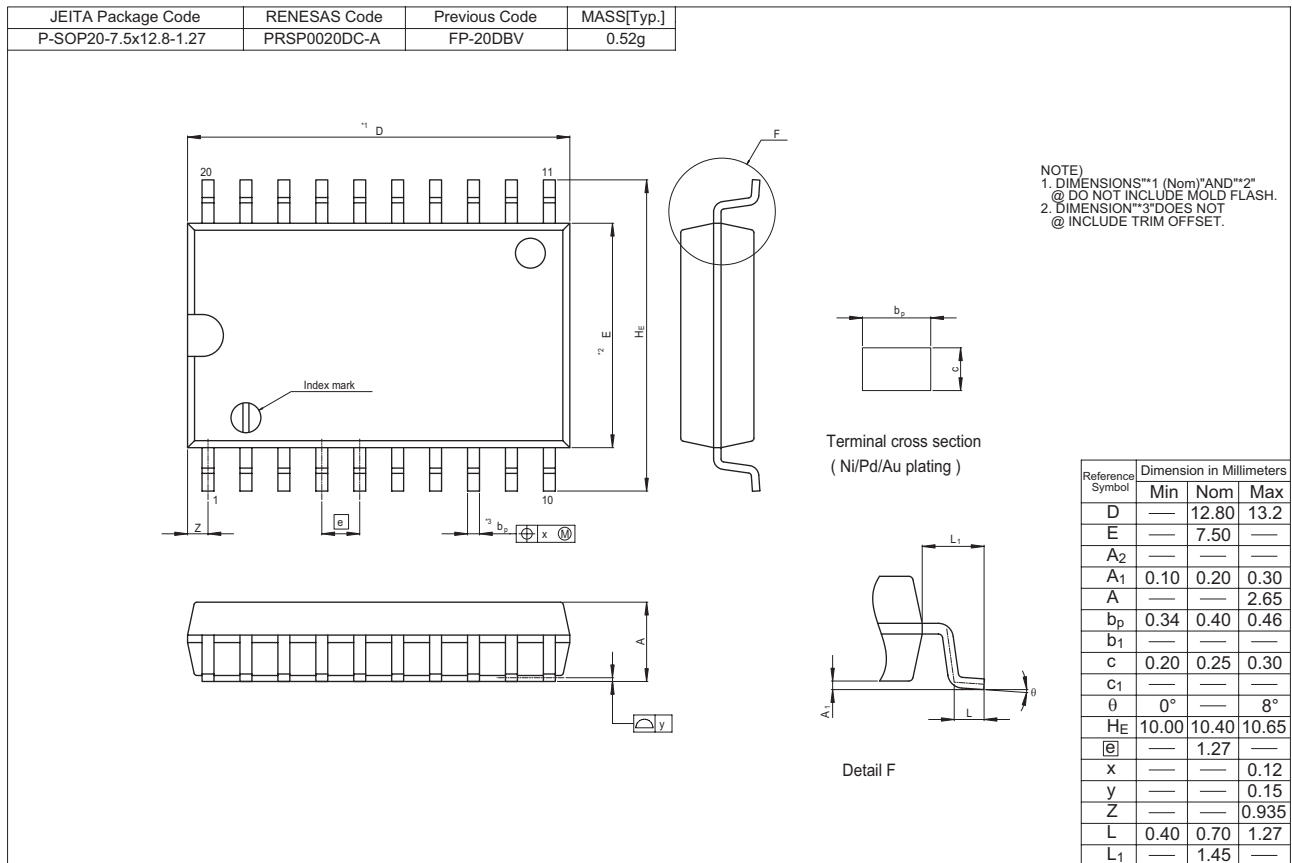
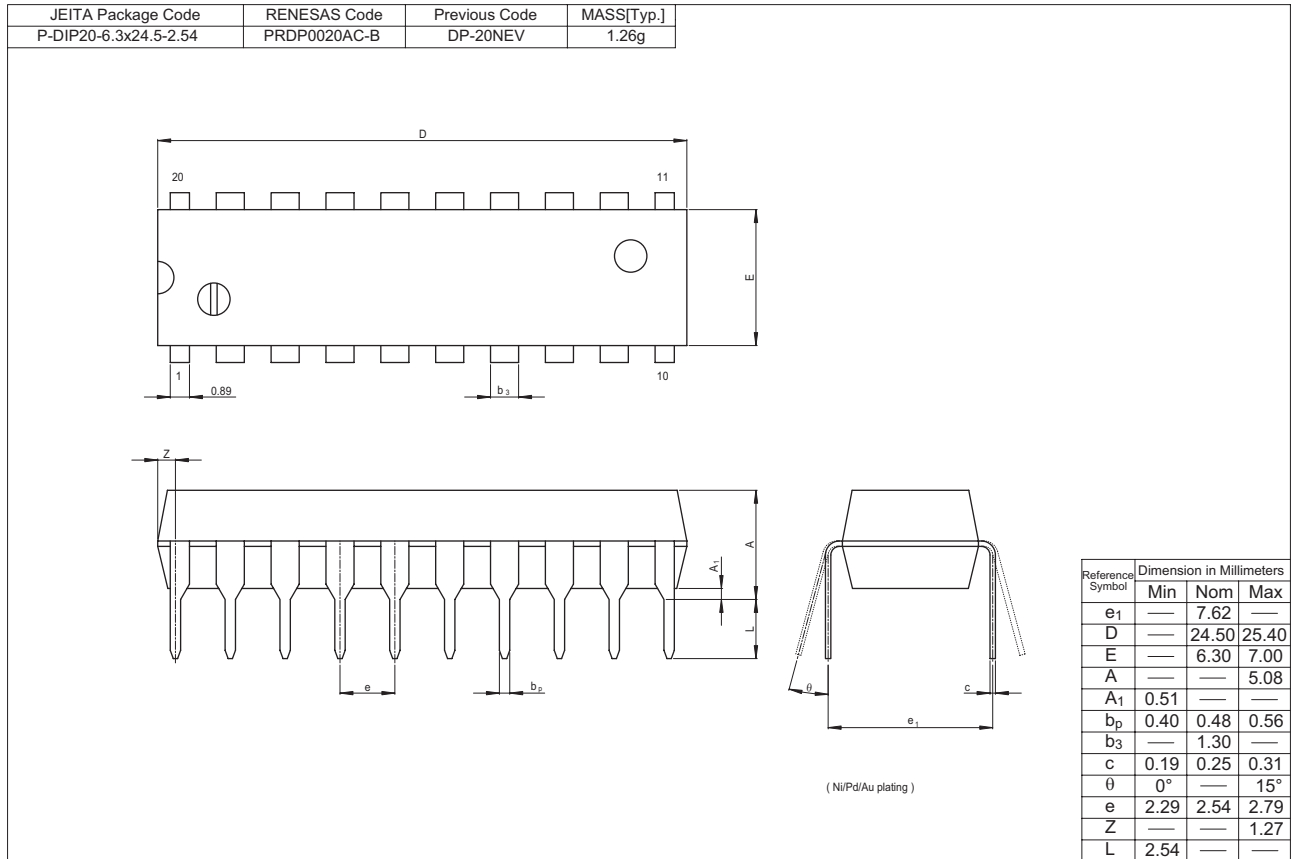


• Waveform –3



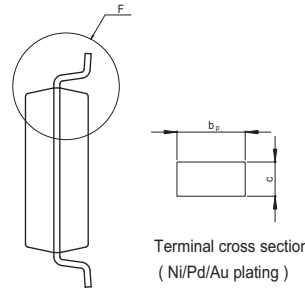
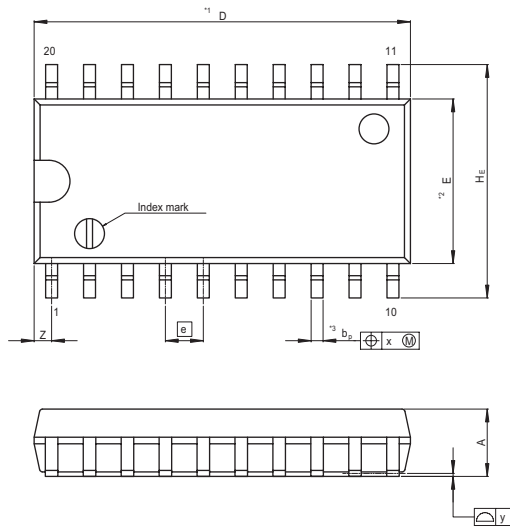
- Notes :
1. Input waveform : $PRR \leq 1 \text{ MHz}$, duty cycle 50%, $t_r \leq 6 \text{ ns}$, $t_f \leq 6 \text{ ns}$
 2. Waveform– A is for an output with internal conditions such that the output is low except when disabled by the output control.
 3. Waveform– B is for an output with internal conditions such that the output is high except when disabled by the output control.
 4. The output are measured one at a time with one transition per measurement.

Package Dimensions

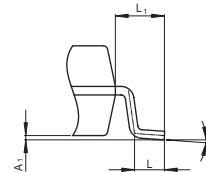


HD74HCT374, HD74HCT534

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP20-5.5x12.6-1.27	PRSP0020DD-B	FP-20DAV	0.31g



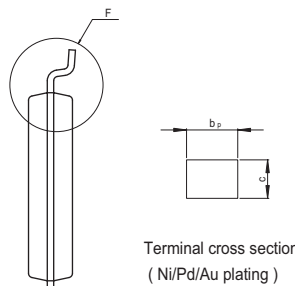
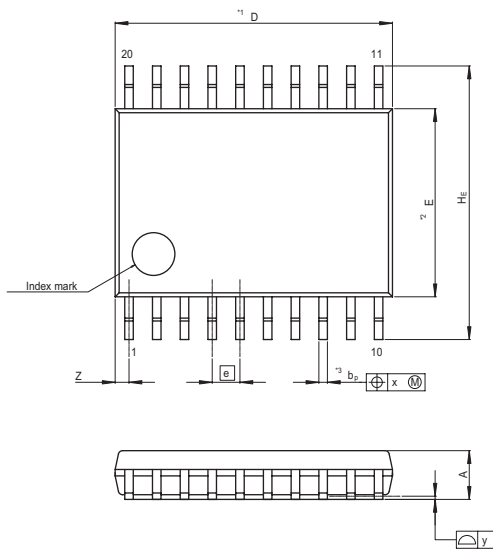
NOTE)
 1. DIMENSIONS**1 (Nom)**AND**2*
 DO NOT INCLUDE MOLD FLASH.
 2. DIMENSION**3*DOES NOT
 INCLUDE TRIM OFFSET.



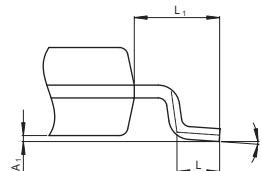
Detail F

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	12.60	13.0
E	—	5.50	—
A ₂	—	—	—
A ₁	0.00	0.10	0.20
A	—	—	2.20
b _p	0.34	0.40	0.46
b ₁	—	—	—
c	0.15	0.20	0.25
c ₁	—	—	—
θ	0°	—	8°
H _E	7.50	7.80	8.00
Ⓜ	—	1.27	—
x	—	—	0.12
y	—	—	0.15
Z	—	—	0.80
L	0.50	0.70	0.90
L ₁	—	1.15	—

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-TSSOP20-4.4x6.5-0.65	PTSP0020JB-A	TTP-20DAV	0.07g



NOTE)
 1. DIMENSIONS**1 (Nom)**AND**2*
 DO NOT INCLUDE MOLD FLASH.
 2. DIMENSION**3*DOES NOT
 INCLUDE TRIM OFFSET.



Detail F

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	6.50	6.80
E	—	4.40	—
A ₂	—	—	—
A ₁	0.03	0.07	0.10
A	—	—	1.10
b _p	0.15	0.20	0.25
b ₁	—	—	—
c	0.10	0.15	0.20
c ₁	—	—	—
θ	0°	—	8°
H _E	6.20	6.40	6.60
Ⓜ	—	0.65	—
x	—	—	0.13
y	—	—	0.10
Z	—	—	0.65
L	0.4	0.5	0.6
L ₁	—	1.0	—

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